

TSMC-00-284B



September 24, 2003

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/613,607 07/03/03

Kuo-Reay Peng, Jian-Hsing Lee

DEPLETION MODE SCR FOR LOW
CAPACITANCE ESD INPUT PROTECTION

Grp. Art Unit: -----

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

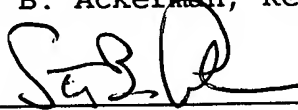
The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on September 26, 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 9/26/03

The following four U.S. Patents pertain to ESD protection:

- 1) U.S. Patent 5,537,284 to Haas, Jr. et al.,
"Electrostatic Discharge Protection Device."
- 2) U.S. Patent 5,821,572 to Walker et al., "Simple BICMOS
Process for Creation of Low Trigger Voltage SCR and
Zener Diode Pad Protection."
- 3) U.S. Patent 5,825,600 to Watt, "Fast Turn-On Silicon
Controlled Rectifier (SCR) for Electrostatic Discharge
(ESD) Protection."
- 4) U.S. Patent 6,074,899 to Voldman, "3-D CMOS-on-SOI ESD
Structure and Method."

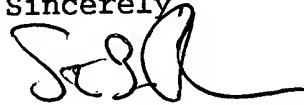
The following three technical reports refer to the subject
of ESD protection in MOS circuits:

- 1) Wu et al., "ESD Protection for Output Pad with Well-
Coupled Field-Oxide Device in 0.5- μm CMOS
Technology," IEEE Transactions on Electron Devices,
Vol. 44, No. 3, pp. 503-508, March 1997, IEEE.

- 2) Ker et al., "ESD Protection Design on Analog Pin with Very Low Input Capacitance for High-Frequency or Current-Mode Applications," IEEE Journal of Solid-State Circuits, Vol. 35, No. 8, pp. 1194-1199, August 2000, IEEE.

- 3) Kleveland et al., "Distributed ESD Protection for High-Speed Integrated Circuits," IEEE Electron Device Letters, Vol. 21, No. 8, pp. 390-392, August 2000, IEEE.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', with a long horizontal flourish extending to the right.

Stephen B. Ackerman,
Reg. No. 37761

Dishes (Number) (Copies)

Hydrogenation reactions

10/613, 607

Logically

Kuo-Reay Peng et al.

Filing Date

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EX-100
IN THE TRIAL

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- [illegible]

2000, IEEE -

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant

SEP 29 1963

Hydrogen Number

10/613, 607

Kuo-Beau Peng et al.

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SEP 29 1963 (several shouts if necessary)

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DOCUMENT NUMBER

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COUNTRY

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SUBCLASS

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- Cleveland et al., "Distributed ESD Protection for High-Speed Integrated Circuits," IEEE Electron Device Letters, Vol. 21, No. 8, Aug. 2000, IEEE.

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.